

**METHODS OF FORMING ELECTRONIC STRUCTURES INCLUDING
CONDUCTIVE SHUNT LAYERS AND RELATED STRUCTURES**

Abstract

5 Methods of forming an electronic structure may include forming a seed layer
on an electronic substrate, and forming a conductive shunt layer on portions of the
seed layer wherein portions of the seed layer are free of the conductive shunt layer. A
conductive barrier layer may be formed on the conductive shunt layer opposite the
seed layer wherein the conductive shunt layer comprises a first material and wherein
10 the barrier layer comprises a second material different than the first material.
Moreover, a solder layer may be formed on the barrier layer opposite the conductive
shunt layer wherein the solder layer comprises a third material different than the first
and second materials. Related structures are also discussed.

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